L Number	Hits	Search Text	DB	Time stamp
1 Number	541619	nickel ni	USPAT;	2004/01/18
			US-PGPUB;	17:36
	ì		EPO; JPO;	
			DERWENT;	! !
	Ì		IBM_TDB	
2	993	buffer with (nickel ni)	USPAT;	2004/01/18
			US-PGPUB;	17:36
			EPO; JPO;	1
	:		DERWENT;	
3	: : 13274800	"5" "6" "7" "8" "9" "10" with (buffer	USPAT;	2004/01/18
: 3		with (nickel ni))	: US-PGPUB;	17:37
		(1120/102 112) /	EPO; JPO;	
		I	DERWENT;	.
	ı		IBM_TDB	İ
4	. 2518	("5" "6" "7" "8" "9" "10") with (buffer	USPAT;	2004/01/18
ļ		with (nickel ni))	US-PGPUB;	18:29
•	I	!	EPO; JPO;	
			DERWENT;	,
: : e	1 2000	(micro micrometer mm nm) with (("5" "6"	IBM_TDB USPAT;	2004/01/18
5	2026	(micro micrometer mm nm) with (("5" "6" "6" "7" "8" "9" "10") with (buffer with	US-PGPUB;	17:44
	!	(nickel ni)))	EPO; JPO;	17.44
ļ		(Higher High)	DERWENT;	
•			IBM TDB	
6	, 3	(chip semiconductor die ic (integrated	USPĀT;	2004/01/18
		adj circuit) dice) same ((micro	US-PGPUB;	17:45
	ļ	micrometer mm nm) with (("5" "6" "7" "8"	EPO; JPO;	
i		"9" "10") with (buffer with (nickel	DERWENT;	,
-	2006	ni))))	IBM_TDB	2004/01/18
7	2086	(thickness measurement thick micro micrometer mm nm) with (("5" "6" "7" "8"	USPAT; US-PGPUB;	2004/01/18 18:30
i .		"9" "10") with (buffer with (nickel ni)))	EPO; JPO;	. 10:30
		J 10 / With (Baller With (Mickel hi)))	DERWENT;	
		•	IBM TDB	<u> </u>
8	13	(chip semiconductor die ic (integrated	USPAT;	2004/01/18
İ		adj circuit) dice) same ((thickness	US-PGPUB;	18:31
	:	measurement thick micro micrometer mm nm)	EPO; JPO;	!
ļ	1	with (("5" "6" "7" "8" "9" "10") with	DERWENT;	
9	. 1	(buffer with (nickel ni))))	IBM_TDB USPAT	2004/01/10
J	1	i	OSPAI	. 2004/01/18 ' 18:14
l 10	141350	' ("5" "6" "7" "8" "9" "10") with (nickel	USPAT;	2004/01/18
1	!	ni)	US-PGPUB;	18:29
ļ	i		EPO; JPO;	;
	1		DERWENT;	
			IBM_TDB	1
. 11	53830	(thickness measurement thick micro	'USPAT;	2004/01/18
		micrometer mm nm) with (nickel ni)	US-PGPUB;	18:30
			EPO; JPO; DERWENT;	
1	•	1	IBM TDB	!
12	i 3954	(chip semiconductor die ic (integrated	USPAT;	2004/01/18
		adj circuit) dice) same ((thickness	US-PGPUB;	18:31
į		measurement thick micro micrometer mm nm)	EPO; JPO;	
1		with (nickel ni))	DERWENT;	i
1.0	5 :		IBM_TDB	!
113	74	((chip semiconductor die ic (integrated	USPAT;	2004/01/18
	i	adj circuit) dice) same ((thickness	US-PGPUB;	18:31
	 	measurement thick micro micrometer mm nm) with (nickel ni))) same buffer	· EPO; JPO; , DERWENT;	
1	ļ	when (micker ma))) same purier	IBM TDB	Ì
ı	-	-	T-1011 100	.: